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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064slc44-7

Email: info@E-XFL.COM

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The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Feat	ures		
Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			\checkmark
JTAG BST circuitry			✓(1)
Open-drain output option			\checkmark
Fast input registers		~	
Six global output enables		~	\checkmark
Two global clocks		~	
Slew-rate control		 	
MultiVolt interface (2)	\checkmark	~	\checkmark
Programmable register	\checkmark	 	
Parallel expanders	\checkmark	 	
Shared expanders	\checkmark	~	\checkmark
Power-saving mode	\checkmark	 	\checkmark
Security bit	\checkmark	✓	\checkmark
PCI-compliant devices available	\checkmark	 ✓ 	

Notes:

(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.

(2) The MultiVolt I/O interface is not available in 44-pin packages.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- 1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- 4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- 5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , \mathbf{t}_{ACL} , and \mathbf{t}_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1} .

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

devices.

Figure 9 shows the timing requirements for the JTAG signals.



Table 12 shows the JTAG timing parameters and values for MAX 7000S

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*).

Table 1	Table 15. MAX 7000 5.0-V Device DC Operating Conditions Note (9)								
Symbol	Parameter	Conditions	Min	Max	Unit				
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V				
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V				
V _{OH}	5.0-V high-level TTL output voltage	I_{OH} = -4 mA DC, V_{CCIO} = 4.75 V (10)	2.4		V				
	3.3-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V} (10)$	2.4		V				
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V} (10)$	V _{CCIO} – 0.2		V				
V _{OL}	5.0-V low-level TTL output voltage	I_{OL} = 12 mA DC, V_{CCIO} = 4.75 V (11)		0.45	V				
	3.3-V low-level TTL output voltage	I_{OL} = 12 mA DC, V_{CCIO} = 3.00 V (11)		0.45	V				
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.0 V(11)		0.2	V				
II.	Leakage current of dedicated input pins	$V_{I} = -0.5$ to 5.5 V (11)	-10	10	μA				
I _{OZ}	I/O pin tri-state output off-state current	V _I = -0.5 to 5.5 V (11), (12)	-40	40	μA				

Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices							
Symbol	Parameter	Parameter Conditions Min					
CIN	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF		
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF		

Table 1	7. MAX 7000 5.0-V Device Capa	acitance: MAX 7000E Devices Not	e (13)		
Symbol	Parameter	Conditions	Min	Max	Unit
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF

Table 1	8. MAX 7000 5.0-V Device Capa	(13)			
Symbol	Parameter	Conditions	Min	Max	Unit
CIN	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF

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MAX 7000 Programmable Logic Device Family Data Sheet

Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is -0.5 V and on 4 dedicated input pins is -0.3 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) V_{CC} must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V_{CCINT} voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V_{CCISP} parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is -0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 μA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices



Timing Model

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Figure 13. Switching Waveforms



Symbol	Parameter	Conditions	Speed	Grade -6	Speed (Unit	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.4		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t _{FIN}	Fast input delay	(2)		0.8		1.0	ns
t _{SEXP}	Shared expander delay			3.5		4.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			2.0		3.0	ns
t _{LAC}	Logic control array delay			2.0		3.0	ns
t _{IOE}	Internal output enable delay	(2)				2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off, V _{CCIO} = 5.0 V	C1 = 35 pF		2.0		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off, V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.5		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on, V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		7.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 5.0 \text{ V}$	C1 = 35 pF		4.0		4.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF (7)		4.5		4.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t _{SU}	Register setup time		3.0		3.0		ns
t _H	Register hold time		1.5		2.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			0.8		1.0	ns
t _{COMB}	Combinatorial delay			0.8		1.0	ns
t _{IC}	Array clock delay			2.5		3.0	ns
t _{EN}	Register enable time			2.0		3.0	ns
t _{GLOB}	Global control delay			0.8		1.0	ns
t _{PRE}	Register preset time			2.0		2.0	ns
t _{CLR}	Register clear time			2.0		2.0	ns
t _{PIA}	PIA delay			0.8		1.0	ns
t _{I PA}	Low-power adder	(8)		10.0		10.0	ns

Symbol	Parameter	Conditions	Speed Grade					
			MAX 700	OE (-10P)	MAX 7000 (-10) MAX 7000E (-10)			
			Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t _{SU}	Global clock setup time		7.0		8.0		ns	
t _H	Global clock hold time		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns	
t _{CH}	Global clock high time		4.0		4.0		ns	
t _{CL}	Global clock low time		4.0		4.0		ns	
t _{ASU}	Array clock setup time		2.0		3.0		ns	
t _{AH}	Array clock hold time		3.0		3.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns	
t _{ACH}	Array clock high time		4.0		4.0		ns	
t _{ACL}	Array clock low time		4.0		4.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns	
t _{CNT}	Minimum global clock period			10.0		10.0	ns	
f _{CNT}	Maximum internal global clock frequency	(5)	100.0		100.0		MHz	
tACNT	Minimum array clock period			10.0		10.0	ns	
f _{acnt}	Maximum internal array clock frequency	(5)	100.0		100.0		MHz	
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz	

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	0E (-12P)	MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t _{SU}	Global clock setup time		7.0		10.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		6.0		6.0	ns
t _{CH}	Global clock high time		4.0		4.0		ns
t _{CL}	Global clock low time		4.0		4.0		ns
t _{ASU}	Array clock setup time		3.0		4.0		ns
t _{AH}	Array clock hold time		4.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		12.0		12.0	ns
t _{ACH}	Array clock high time		5.0		5.0		ns
t _{ACL}	Array clock low time		5.0		5.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	5.0		5.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			11.0		11.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	90.9		90.9		MHz
t _{ACNT}	Minimum array clock period			11.0		11.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	90.9		90.9		MHz
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz

Symbol	Parameter	Conditions	Speed Grade					
			MAX 700	IOE (-12P)	MAX 70 Max 70	100 (-12) Doe (-12)		
			Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			1.0		2.0	ns	
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns	
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns	
t _{SEXP}	Shared expander delay			7.0		7.0	ns	
t _{PEXP}	Parallel expander delay			1.0		1.0	ns	
t _{LAD}	Logic array delay			7.0		5.0	ns	
t _{LAC}	Logic control array delay			5.0		5.0	ns	
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns	
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns	
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns	
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns	
t _{ZX1}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0 V$	C1 = 35 pF		6.0		6.0	ns	
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		7.0		7.0	ns	
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		10.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns	
t _{SU}	Register setup time		1.0		4.0		ns	
t _H	Register hold time		6.0		4.0		ns	
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns	
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns	
t _{RD}	Register delay			2.0		1.0	ns	
t _{COMB}	Combinatorial delay			2.0		1.0	ns	
t _{IC}	Array clock delay			5.0		5.0	ns	
t _{EN}	Register enable time			7.0		5.0	ns	
t _{GLOB}	Global control delay			2.0		0.0	ns	
t _{PRE}	Register preset time			4.0		3.0	ns	
t _{CLR}	Register clear time			4.0		3.0	ns	
t _{PIA}	PIA delay			1.0		1.0	ns	
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade								Unit
			-	-5		6	-7		-10		1
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t ACNT	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 28. EPM7032S Internal Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade U								Unit
			-	5	-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 29. EPM7064S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	s Speed Grade								Unit
			-	5	-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns

Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions		Speed Grade U							
			-	6	-7		-10		-15		
			Min	Max	Min Max		Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more (1)information on switching waveforms.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter (2)must be added to this minimum width if the clear or reset signal incorporates the t_{IAD} parameter into the signal path.

This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This (3) parameter applies for both global and array clocking.

These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB. (4)

- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use. (6)

For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, (7)these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8)The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)										
Symbol	Parameter	Conditions	Speed Grade							
			-7		-10		-15			
			Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns	
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns	
t _{CH}	Global clock high time		3.0		4.0		5.0		ns	
t _{CL}	Global clock low time		3.0		4.0		5.0		ns	
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns	

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I_{CCINT} value, which depends on the switching frequency and the application logic, is calculated with the following equation:

 $I_{CCINT} =$

 $A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{LC}$

The parameters in this equation are shown below:

MC _{TON}	=	Number of macrocells with the Turbo Bit option turned on,
		as reported in the MAX+PLUS II Report File (.rpt)
MC _{DEV}	=	Number of macrocells in the device
MC _{USED}	=	Total number of macrocells in the design, as reported
		in the MAX+PLUS II Report File (.rpt)
f _{MAX}	=	Highest clock frequency to the device
tog _{LC}	=	Average ratio of logic cells toggling at each clock
		(typically 0.125)
A, B, C	=	Constants, shown in Table 39



Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 2 of 2)

Figure 15 shows typical supply current versus frequency for MAX 7000S devices.



Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



84-Pin PLCC

Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

